



First Call for Papers

9th International Conference on Solid-State and Integrated-Circuit Technology ICSICT' 2008, October 20-23, 2008, Beijing, China

Co-Sponsored by:

IEEE Beijing Section
Chinese Institute of Electronics (CIE)

Technical Co-Sponsored by

IEEE Electron Devices Society
IEEE EDS Beijing Chapter

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The 2008 ICSICT conference is the ninth of its kind aiming to provide an international forum for the presentation and discussion of recent advances in solid-state and integrated circuit technology. The conference will be held during October 20-23, 2008 in Beijing, China.

All aspects of solid-state devices, circuits, processing technologies, materials and other related research are within the scope of the conference. The three days of contributed and invited presentations on the latest developments in diverse fields given in oral and poster sessions, panel discussions on leading edge technology issues, and other activities will provide extensive opportunities for technical information exchange as well as a stimulating environment for mutual communication among participants. There will be discussions devoted to opportunities for cooperation and joint ventures in the microelectronics business in China. Best Student Paper Award will be issued at the closing of the conference.

The Scope and Topics of the Conference

(Papers are solicited in, but not limited to the following areas)

Silicon/Germanium/III-V IC devices; Advanced process technology; Silicon integrated circuits manufacturing; Advanced memory technologies; Compound semiconductor devices and circuits; Device and interconnect reliability; Modeling and simulation; Semiconductor materials and material characterization; Quantum electronics and nano-electronics; Photonic devices and technologies; Sensors and MEMS; ASICs and SOC design technologies; Low power circuits; Digital, analog and mixed-signal circuits; RF and microwave circuits; EDA and DFM technologies; Testing and DFT technologies; Organic semiconductor devices and technologies; Packaging and assembly technologies; Equipment technology; Others;

Paper Submission:

Prospective authors are requested to submit full-length papers in English of no more than four pages. The papers are to be submitted in final form and, if accepted, will be published as submitted. On-line electric submission is preferred. Detailed instructions for paper preparation and submission can be found at web-site of the conference.

Deadline for Submission: May 31, 2008

Web-site : <http://www.ime.pku.edu.cn/icsict>

Email Address: icsict2008@ime.pku.edu.cn